

Post-Show Report 2012

Inside NEPCON JAPAN

41st
INTERNEPCON JAPAN

29th
ELECTROTEST JAPAN

ICP 13th **IC PACKAGING
 TECHNOLOGY EXPO**

13th
 INTERNATIONAL ELECTRONIC COMPONENTS TRADE SHOW
ELE TRADE 2012

PWB EXPO
 13th Printed Wiring Boards Expo

MATERIAL JAPAN
 3rd Advanced Electronic Materials Expo

MicroTech JAPAN
 2nd Micro Fabrication/
 Fine Process Technology Expo

Concurrent Shows

**AUTOMOTIVE
 WORLD** 2012

4th **LED/OLED Lighting
 Technology Expo**
LIGHTING JAPAN

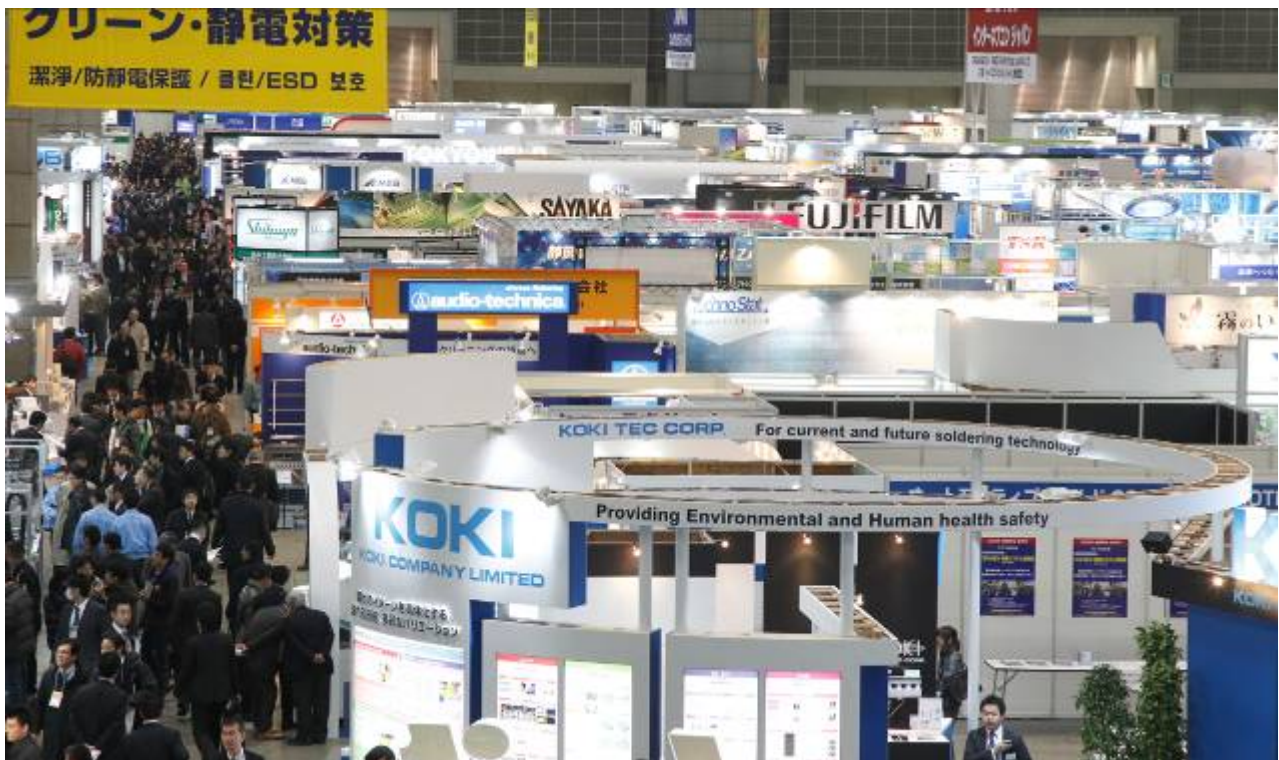


TABLE OF CONTENTS

■ Exhibition Outline	-----	1
■ Show Highlight	-----	2
■ Technical Conference	-----	4
■ Next Shows in 2013	-----	5

Exhibition Outline

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Exhibition Title	NEPCON JAPAN 2012 - 41st Electronics R&D and Manufacturing Technology Expo -41 st INTERNEPCON JAPAN -29 th ELECTROTEST JAPAN -13 th IC PACKAGING TECHNOLOGY EXPO -13 th INTERNATIONAL ELECTRONIC COMPONENTS TRADE SHOW(ELE TRADE 2012) -13 th Printed Wiring Boards Expo (PWB EXPO) -3 rd Advanced Electronic Materials Expo (MATERIAL JAPAN) -2 nd Micro Fabrication/Fine Process Technology Expo (MicroTech JAPAN)
Dates	Jan 18 (Wed) -20(Fri), 2012
Venue	Tokyo Big Sight, Japan
Concurrent Events	Technical Conference
Concurrent Shows	AUTOMOTIVE WORLD 2012 LIGHTING JAPAN-4 th LED/OLED Lighting Technology Expo
Total Exhibit Space	80,660m ² (Including Concurrent Shows)
Organised by	Reed Exhibitions Japan Ltd.

FACT SHEET	
Number of Exhibitors	1,217
Number of Visitors	59,963
Number of Press Members	550
Number of Seminar Participants	8,122

(Including AUTOMOTIVE WORLD)

<http://www.nepconjapan.jp/en/doc/TAC/>



ASIA'S LARGEST Exhibition for Electronics Design, R&D and Manufacturing

NEPCON JAPAN 2012 - 41st Electronics R&D and Manufacturing Technology Expo (Abbreviation: NEPCON JAPAN) is Asia's LARGEST electronics trade show gathering machines and equipment for manufacturing and SMT, as well as components and materials for R&D and design. Consisting of the 7 exhibitions, it was held on January 18[Wed] – 20[Fri], 2012 in Tokyo Big Sight, Japan.

NEPCON JAPAN is known as the perfect venue to experience the leading-edge technologies and products in electronics industry and conduct business meeting and consultations, attracting unrivalled number of visitors from electronics assembly manufacturers, semiconductor manufacturers, automotive/device manufacturers from both domestic market and abroad. Particularly, in 2012, it concluded with a great success with a record number of 1,217* exhibitors and 59,963* visitors. (*including AUTOMOTIVE WORLD.)

There are also two concurrent shows of NEPCON JAPAN, namely the AUTOMOTIVE WORLD 2012, and LIGHTING JAPAN- 4th LED/OLED Lighting Technology Expo. Both of them cover the hot topics of the main applications utilizing the electronics technologies in automotive and emerging LED/OLED lighting industry. NEPCON JAPAN and its concurrent shows attract great attention from industrial specialists, press and receive very positive comments from exhibitors and visitors.

NEPCON JAPAN 2013 is under vigorous preparation now and many of the exhibitors have already booked their spaces. For details, please refer to the following chapters.

Show Highlight

NEPCON JAPAN - The EXHIBITION and CONFERENCE-

NEPCON JAPAN covers all of the relevant areas of electronics industry. In NEPCON JAPAN 2012 the products and technologies include the following devices, modules, and materials.

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| <input type="checkbox"/> Mounters | <input type="checkbox"/> Board Vision Inspection Equipment |
| <input type="checkbox"/> Test / Analysis / Measurement Equipment | <input type="checkbox"/> Assembly Equipment |
| <input type="checkbox"/> Soldering Machines | <input type="checkbox"/> Packaging Materials/Components |
| <input type="checkbox"/> Cleaning Equipment | <input type="checkbox"/> General Electronic Components |
| <input type="checkbox"/> Dry Cleaning | <input type="checkbox"/> sensors |
| <input type="checkbox"/> Factory/Facility Equipment | <input type="checkbox"/> PWBs/PCBs |
| <input type="checkbox"/> Material Handling Equipment | <input type="checkbox"/> PCB Materials |
| | <input type="checkbox"/> Electronic Materials etc. |

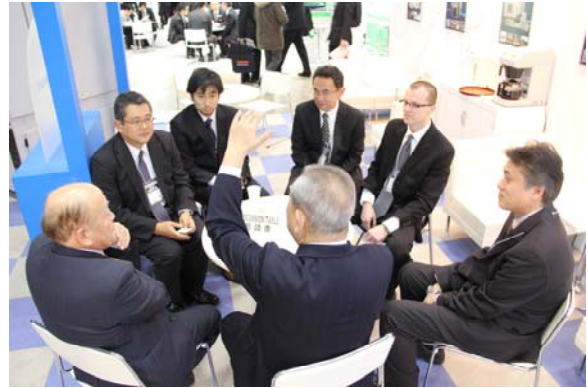
Gathering of Test, Inspection, and Measurement Leading Companies:

As slimmer and highly-functional mobile devices for Smartphone's are becoming more and more important to achieve high-density packaging technologies, the interest and reliability of the testing techniques are also increasing each year.

Evidently, a large majority of exhibitors; many whom which are leaders of this area of expertise exhibited such products and demonstrated new technologies.

Along side OMRON, NAGOYA ELECTRIC WORKS, and Saki Corporation who exhibit every year, new comers such as SANKO TSUSHO and TOYOTSU MACHINERY exhibited Appearance Inspection Equipment Industry leader KUSUMOTO Chemicals, also a new exhibitor for NEPCON JAPAN exhibited a cutting edge testing equipment with the ability to work under various conditions.

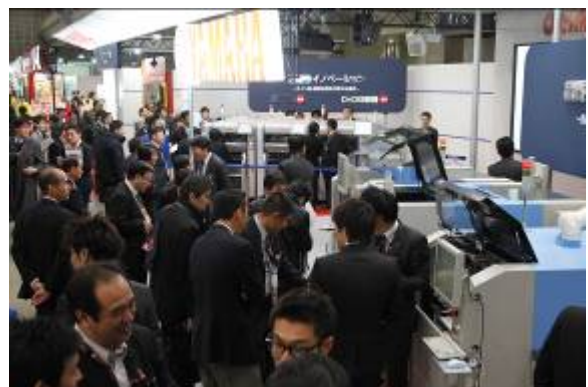
These exhibitors were a great hit during the show.



Power electronics zone is expanding the size!

As environmental and energy issues such as global warming and oil inflation are becoming a major concern, highly efficient eco-friendly technologies are grabbing people's attention.

Nippon Kayaku exhibited heat-dissipation resin for heat dissipation at high currents. KYOTO DENKI, AVERY DENNISON JAPAN MATERIALS, NAGASE INTEGREGX, who newly exhibit this year focused on power electronics, a major area which is expected to grow in the future.



Technical Conference

Every year, "Technical Conference" wins great popularity as a concurrent event of the exhibition. In 2012, there were 48 sessions in total, and 135 speakers were invited (including AUTOMOTIVE WORLD). A great number of industry professionals participated in those sessions to get the latest industry trends, cutting-edge technologies and companies' strategies.

KEYNOTE SESSION

※Simultaneous Interpretation:
English/Chinese/Japanese/Korean



INTERNEPCON JAPAN Keynote Session Date: Jan. 18 [Wed] 13:30-15:00

<p>Perspective Direction for Electronic System View from Super High Band Communication</p>  <p>Kanji Otsuka Emeritus Professor, Advisor, Collaborative Research Center of Meisei University</p>	<p>Fujitsu's Technology that Developed the "K Computer"</p>  <p>Hideyuki Saso Corporate Senior Executive Vice President, Fujitsu Ltd.</p>
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IC PACKAGING TECHNOLOGY EXPO Keynote Session Date: Jan. 19 [Thur] 10:00-11:30

<p>Evolution of Semiconductor: For Future Society and New User Experience</p>  <p>Tsuyoshi Abe Director and Vice President, and General Manager of Technology & Manufacturing Group, Intel K.K.</p>	<p>Amkor Strategy for Packaging Technology</p>  <p>Choon-Heung Lee Corporate Vice President, Head of Corp. Technology HQ, Amkor Technology Korea, Inc.</p>
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Printed Wiring Boards Expo Keynote Session Date: Jan. 19 [Thur] 13:30-15:00

<p>The strategy of NTT DOCOMO's Smartphone</p>  <p>Kiyohito Nagata Senior Vice President, Managing Director, Strategic Marketing Dept., NTT DOCOMO, Inc.</p>	<p>Toward a Dream TV -Toshiba's Strategy and 3D Technologies-</p>  <p>Takashi Kamitake Chief Fellow, Corporate Research & Development Center, Toshiba Corp.</p>
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AUTOMOTIVE WORLD Keynote Session Date: Jan. 18 [Wed] 10:30-12:30

<p>Rapidly Changing Automotive Industry and its Expectations for Car Electronics</p> <p>Moritaka Yoshida Managing Officer, Toyota Motor Corp.</p> 	<p>Volkswagen Group Strategy for Electric Mobility</p> <p>Rudolf Krebs Executive Vice President, Head of Group E-Traction, Volkswagen AG</p> 	<p>Ford's Sustainable Electrification Approach</p> <p>Nancy Gioia Director, Global Electrification, Ford Motor Company</p> 
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Next Shows in 2013

NEPCON JAPAN will keep expanding in the number of exhibitors and visitors, as it always has. From **Jan 16th to 18 in 2013** the 42nd NEPCON JAPAN will be held grandly with AUTOMOTIVE WORLD 2013 and LIGHTING JAPAN 2013 (the 5th LED/OLED Lighting Technology Expo) in Tokyo Big Sight.

As the central place of the latest electronics technologies, the shows have come under the spotlight among industry professionals as a must-attend event. The shows recorded the largest number of exhibitors and visitors this year. Most of participants were satisfied with their business results, and in fact, show management has received many positive comments from them.

If you are interested in exhibiting at this event, please contact us immediately. The exhibit space is limited and it is expected to be sold out at an early stage. Also, if you have interest in visiting the show, please pre-register via website. Click the "Visitor Pre-registration" banner on the official website, fill out the form, and press "submit" button. After that, you will receive the newest information by e-mail or airmail.

Next Show Dates

Dates: January 16 [Wed] - 18 [Fri], 2013

Venue: Tokyo Big Sight, Japan

Organised by: Reed Exhibitions Japan Ltd.

2013 Show Outline

NEPCON JAPAN 2013 - 42nd Electronics R&D and Manufacturing Technology Expo

- * 42nd INTERNEPCON JAPAN
- * 30th ELECTROTEST JAPAN
- * 14th IC PACKAGING TECHNOLOGY EXPO
- * ELE TRADE 2013-14th INTERNATIONAL ELECTRONIC COMPONENTS TRADE SHOW
- * PWB EXPO-14th Printed Wiring Boards Expo
- * MATERIAL JAPAN-4th Advanced Electronic Materials Expo
- * MicroTech JAPAN-3rd Micro Fabrication / Fine Process Technology Expo

For any other inquiries, please feel free to contact us.
We are looking forward to seeing you at the show in 2013.

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